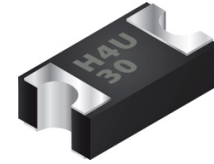


# MATERIAL DECLARATION SHEET

**BOURNS®**

|                 |                        |     |   |                                                                                     |
|-----------------|------------------------|-----|---|-------------------------------------------------------------------------------------|
| Material Number | SMF4C SERIES           |     |   |  |
| Product Line    | Semiconductor Products |     |   |                                                                                     |
| Compliance Date | 2025/4/30              |     |   |                                                                                     |
| RoHS Compliant  | Yes                    | MSL | 1 |                                                                                     |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [mg] | Homogeneous Material\                    | CASRN         | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|-----|-------------------------------|----------------------|----------------------|------------------------------------------|---------------|------------------|-----------------------------------|-------------------------------|
|     |                               |                      |                      | Substances                               | if applicable |                  |                                   |                               |
| 1   | FRP                           | Metal                | 14.6                 | Copper                                   | 7440-50-8     | 97.4125          | 71.111125                         | 73.00                         |
|     |                               |                      |                      | Iron                                     | 7439-89-6     | 2.35             | 1.7155                            |                               |
|     |                               |                      |                      | Phosphorus                               | 7723-14-0     | 0.0825           | 0.060225                          |                               |
|     |                               |                      |                      | Zinc                                     | 7440-66-6     | 0.125            | 0.09125                           |                               |
|     |                               |                      |                      | Lead                                     | 7439-92-1     | 0.03             | 0.0219                            |                               |
| 2   | Epoxy                         | Plastic              | 3.5                  | Bis-Phenol Type Liquid Epoxy             | 9003-36-5     | 30.516           | 5.3403                            | 17.50                         |
|     |                               |                      |                      | Hexahydro-4-methylphthalic anhydride [2] | 19438-60-9    | 30.516           | 5.3403                            |                               |
|     |                               |                      |                      | Silicon Dioxides (Silica)                | 7631-86-9     | 38.968           | 6.8194                            |                               |
| 3   | Solder Cream                  | Metal                | 0.2                  | Lead                                     | 7439-92-1     | 92.38            | 0.9238                            | 1.00                          |
|     |                               |                      |                      | Tin                                      | 7440-31-5     | 4.35             | 0.0435                            |                               |
|     |                               |                      |                      | Rosin, Hydrogenated                      | 65997-06-0    | 1                | 0.01                              |                               |
|     |                               |                      |                      | Silver                                   | 7440-22-4     | 2.27             | 0.0227                            |                               |
| 4   | Dice                          | Others               | 1.3                  | Silicon                                  | 7440-21-3     | 90.566           | 5.8868                            | 6.50                          |
|     |                               |                      |                      | Phosphorous                              | 7723-14-0     | 0.105            | 0.0068                            |                               |
|     |                               |                      |                      | Boron                                    | 7440-42-8     | 0.019            | 0.0012                            |                               |
|     |                               |                      |                      | Aluminum                                 | 7429-90-5     | 1.990            | 0.1294                            |                               |
|     |                               |                      |                      | Titanium                                 | 7440-32-6     | 0.825            | 0.0536                            |                               |
|     |                               |                      |                      | Nickel                                   | 7440-02-0     | 2.620            | 0.1703                            |                               |
|     |                               |                      |                      | Silver                                   | 7440-22-4     | 3.875            | 0.2519                            |                               |
| 5   | Terminal Plating              | Metal                | 0.4                  | Tin                                      | 7440-31-5     | 100              | 2.0000                            | 2.00                          |

# MATERIAL DECLARATION SHEET

**BOURNS®**

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|              |      |
|--------------|------|
| Total weight | 20.0 |
|--------------|------|

This Document was updated on: 2025/4/30

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. E Excepted for RoHS 7(a)-III Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead) in first level solder joints (internal or integral connections - meaning internal and external) for manufacturing components so that subsequent mounting of electronic components onto subassemblies (i.e. modules. Sub-circuit boards, substrates, or point-to-point soldering) with a secondary solder does not reflow the first level solder. This sub-entry excludes die attach.